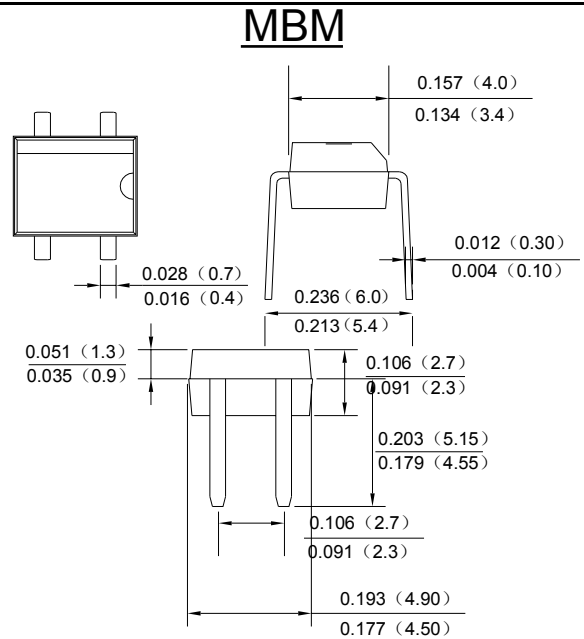


Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.
 Single Phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	UMB1M	UMB2M	UMB4M	UMB6M	UMB8M	UMB10M	UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V _{RWM}							
DC Blocking Voltage	V _{DC}							
RMS Reverse Voltage	V _{RMS}	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T _A =40°C (Note 2)@T _A =40°C	I _O	0.5 0.8						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30						A
Forward Voltage per element @IF=0.8A	V _{FM}	1.0		1.3		1.7		V
Peak Reverse Current @T _A =25°C At Rated DC Blocking Voltage @T _A =125°C	I _R	5.0 500						uA
Maximum reverse recovery time (Note 3)	T _{RR}	50			75			ns
Typical Junction Capacitance per leg	C _J	13						pF
	R _{θJA}	70						
Typical Thermal Resistance per leg (Note 4)	R _{θJL}	20						°C/W
Operating and Storage Temperature Range	T _J ,T _{STG}	-55to+150						°C

- Note:1. Mounted on glass epoxy PC board with 1.3mm² solder pad.
 2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.
 3. Reverse Recovery Test Conditions: IF=0.5A, IR=1A, Irr=0.25A.
 4. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

UMB1M THRU UMB10M

Fig. 1 Output Current Derating Curve

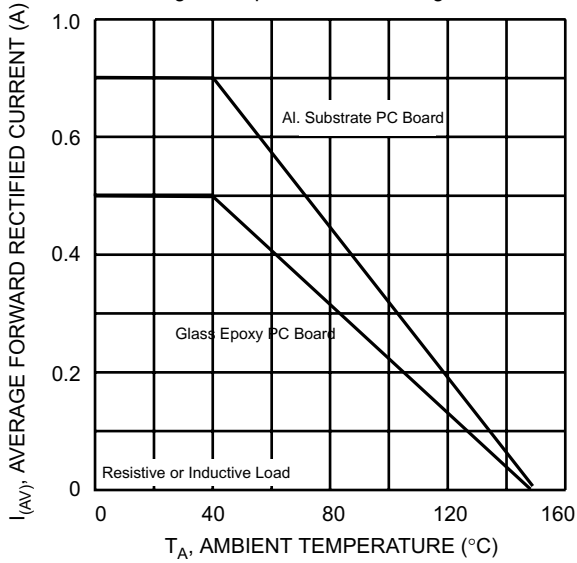


Fig. 2 Typical Forward Characteristics (per leg)

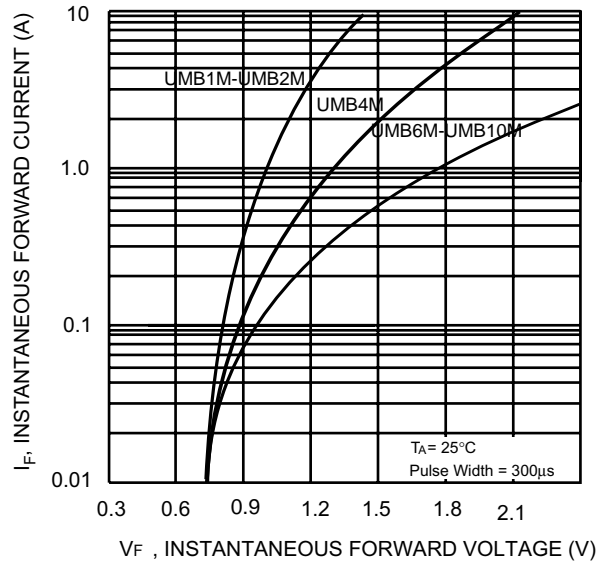


Fig. 3 Maximum Peak Forward Surge Current (per leg)

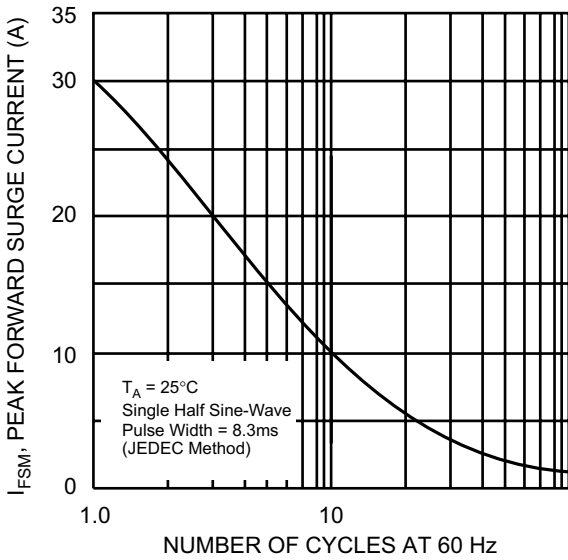


Fig. 4 Typical Junction Capacitance

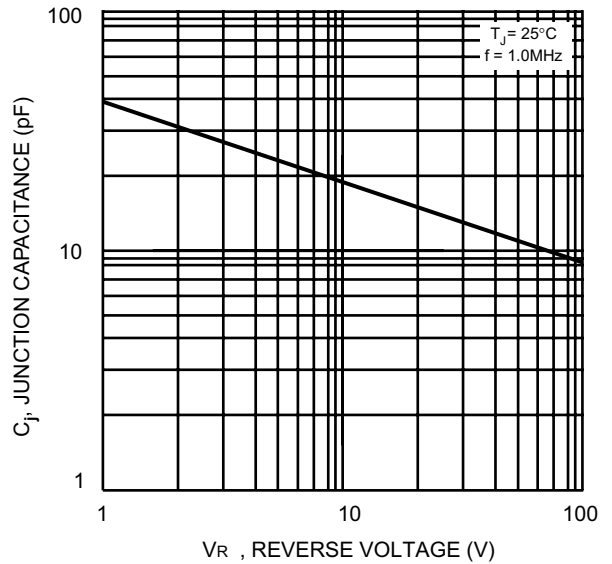


Fig. 5 Typical Reverse Characteristics (per element)

